

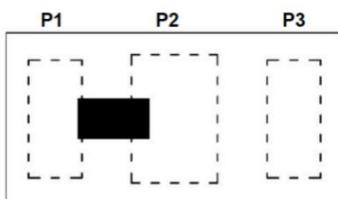
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

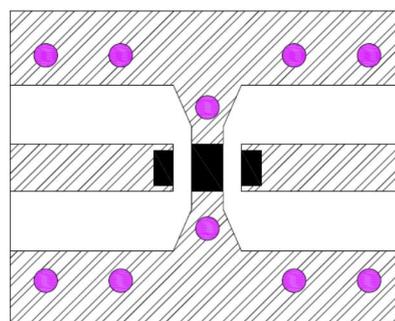
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	1805~2025			2.0
2	VSWR				2.0
3	Attenuation (dB)	700~950	30		
		950~1050	15		
		2400~2500	25		
		2700~5400	30		
		5500~6200	25		
		9350~10150	15		
	5850~12750	20			
4	In/Output Impedance ( $\Omega$ )		50		
5	Permissible Input Power (W)				2
<b>Operating &amp; Storage Condition (Component)</b>					
Operation Temperature Range: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$					
Storage Temperature Range: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$					
<b>Storage Condition before Soldering (Included packaging material)</b>					
Storage Temperature Range: $+5 \sim +40^{\circ}\text{C}$					
Humidity: 30 to 70% relative humidity					

### Construction



PIN	Connection
P1	Input port
P3	GND
P2	Output port

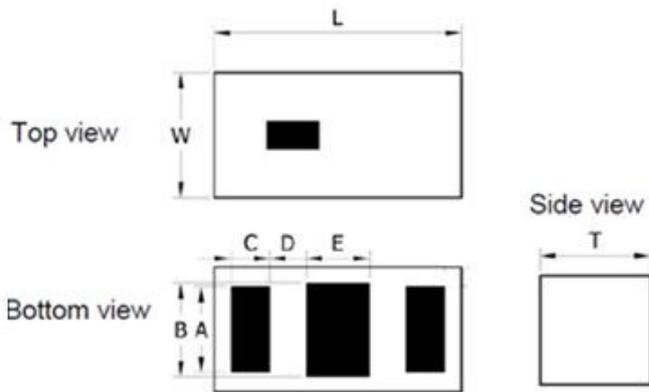
### Mounting Considerations



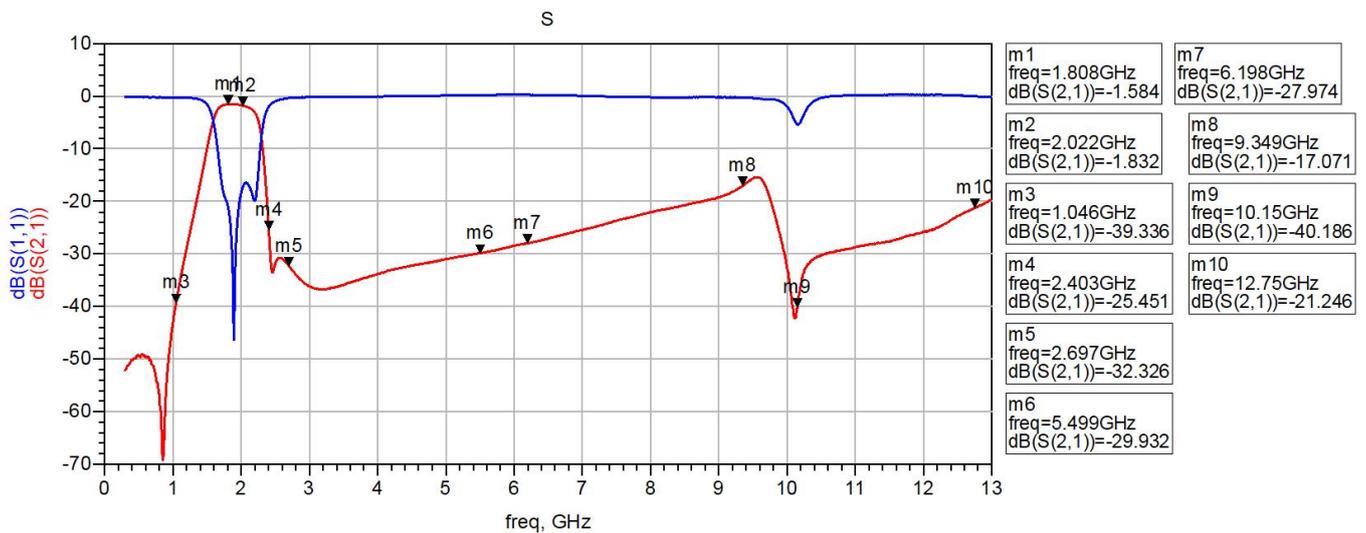
- Land
- ▨ Solder
- Through-hole

Unit: mm  
Line width to be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness

### Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60±0.10
	W	0.80±0.10
	T	0.60±0.10
	A	0.70±0.10
	B	0.70±0.10
	C	0.27±0.10
	D	0.28±0.10
E	0.40±0.10	

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.